


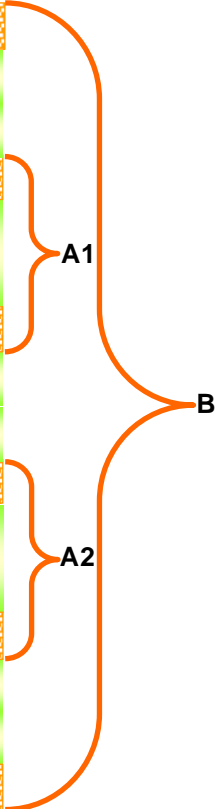


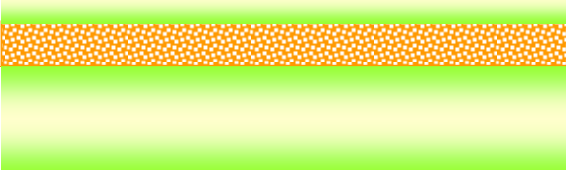









Schematic Key for Multilayer and HDI-Technology Build-Ups

| a | b | c | d | e | f | g + h + i |
|---|---|---|---|---|---|-----------|
|---|---|---|---|---|---|-----------|

06 180 FR4 55 L36.70 P11

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_180_FR4_55_L36.70_p11

| Layers | in μ | Material | Build-Up | Assembly |
|-----------------|-----------|----------|--|--|
| Layer-1 | 55 μ | Copper |  |  |
| | 115 μ | Prepreg | (115 μ PrePreg-Type: 2116) | |
| | 115 μ | Prepreg |  | |
| Layer-2 | 70 μ | Copper |  | |
| | 360 μ | L-FR4 |  | |
| Layer-3 | 70 μ | Copper |  | |
| | 115 μ | Prepreg |  | |
| | 115 μ | Prepreg |  | |
| Layer-4 | 70 μ | Copper |  | |
| | 360 μ | L-FR4 |  | |
| Layer-5 | 70 μ | Copper |  | |
| | 115 μ | Prepreg |  | |
| | 115 μ | Prepreg |  | |
| Layer-99 | 55 μ | Copper |  | |

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